PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KAZUTOSHI SAKO	01/27/2012
TOMOKAZU MATSUZAKI	01/27/2012

RECEIVING PARTY DATA

Name:	RENESAS ELECTRONICS CORPORATION
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14693133

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NAME OF SUBMITTER:	ERIC JENSEN
SIGNATURE:	/Eric Jensen/
DATE SIGNED:	04/22/2015

Total Attachments: 1
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ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that: Appln. No. 14/693,133 Filed on April 22, 2015

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable
consideration paid to me citizen of Japan by Renesas Electronics Corporation,
a corporation organized under the laws of Japan,
located at   1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CONSTANT CURRENT GENERATION CIRCUIT AND MICROPROCESSOR INCLUDING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the
application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters
Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest
being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Renesas Electronics Corporation,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be
granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale
had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and
proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing,
continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment,
extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said
Renesas Electronics Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) *Kazutoshi Sako* Kazutoshi SAKO	*January 27 2012*
2) *Tomokazu Matsuzaki* Tomokazu MATSUZAKI	*January 27 2012*
3)	
4)	
5)	
6)	
7)	
8)	
9)	